- Complete Discrete Multitone (DMT)-Based Asymmetric Digital Subscriber Line (ADSL) Coder/Decoder (CODEC) Solution
- Complies With ANSI T1.413 Issue II and ITU G.992.1
- Supports up to 8 MBPS Downstream and 800 KBPS Upstream Duplex
- Integrated 14-Bit Converters for Transmitter/Echo-Canceller/Receiver (TX/EC/RX)
- Integrated 12-Bit DAC for VCXO Control
- Integrated TX/EC/RX Channel Filters
- Integrated TX/EC/RX Attenuation/Gain

- Integrated Voltage Reference
- High-Speed Parallel Interface
- 16-bit 2s Complement Data Format
- Selectable 2.2 MSPS or 4.4 MSPS Parallel Data Transfer Rate
- Serial Configuration Port
- Eight General-Purpose Output Pins
- Single 3.3-V Supply
- Hardware/Software Power Down
- 100-Pin PQFP (PZ) Package
- –40°C to 85°C Operation

description

The TLV320AD11A is a high-speed codec for remote terminal-side (RT) modems that support the ANSI T1.413 [Issue 2 discrete multi-tone (DMT) asymmetric digital subscriber line (ADSL) access] and ITU G.992.1 standards. It is a low-power device that includes five major functional blocks: transmitter, receiver, clock, reference, and host interface. It is designed to work with the Texas Instruments TLV320AD12 central office-side (CO) codec.

The device's transmit channel consists of the following functional blocks: 138 kHz digital low-pass filter, bypassable 25.875 kHz digital high-pass filter, 14-bit high speed DAC, 138 kHz analog low-pass filter, transmit attenuator, and an echo cancellation channel. The receiver channel consists of two programmable-gain amplifiers, a frequency equalizer, a 1.104-MHz low-pass analog filter, a 14-bit high speed ADC, and a 1.104-MHz low-pass digital filter. The clock circuit divides a 35.328-MHz frequency from an external VCXO down to the necessary frequencies used throughout the device. The frequency of the external VCXO is controlled by a 12-bit onboard voltage output DAC. An onboard reference circuit generates a 1.5-V reference for the converters.

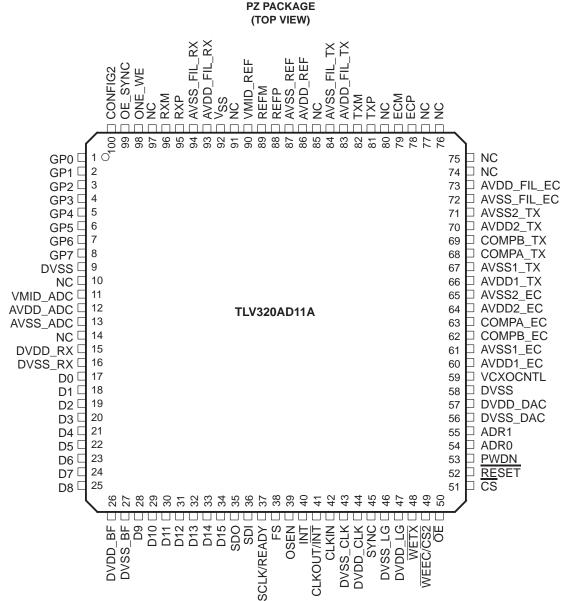
The device has a parallel port for data transfer and a serial port for control. The parallel port is 16 bits wide and is reserved for moving data between the codec and a DSP such as the Texas Instruments TMS320C6XX. Configuration is done via a serial port. The device can be powered down via a dedicated pin, or through software control, to reduce heat dissipation. Additionally, there is a general-purpose (GP) port consisting of eight output terminals for control of external circuitry.

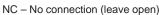
The TLV320AD11A codec is available in a 100-pin PZ PQFP package and is characterized for operation in the temperature range of –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.









Terminal Functions

TERMINAL								
NAME	NO.	1/0	DESCRIPTION					
ADR0 ADR1	54 55	I	Serial port chip ID address bits, ADR0 is the least significant bit.					
AVDD1_EC	60	ı	EC channel analog power supply #1					
AVDD2_EC	64	ı	EC channel analog power supply #2					
AVDD1_TX	66	ı	TX channel analog power supply #1					
AVDD2_TX	70	ı	TX channel analog power supply #2					
AVDD_ADC	12	ı	Receive channel analog power supply					
AVDD_FIL_EC	73	ı	EC channel filter analog power supply					
AVDD_FIL_RX	93	ı	Receive channel filter analog power supply					
AVDD_FIL_TX	83	ı	Transmit channel filter analog power supply					
AVDD_REF	86	ı	Reference analog power supply					
AVSS1_EC	61	ı	EC channel analog ground # 1					
AVSS2_EC	65	ı	EC channel analog ground #2					
AVSS1_TX	67	ı	TX channel analog ground #1					
AVSS2_TX	71	ı	TX channel analog ground #2					
AVSS_ADC	13	ı	Receive channel analog ground					
AVSS_FIL_EC	72	ı	EC channel filter analog ground					
AVSS_FIL_RX	94	ı	Receive channel filter analog ground					
AVSS_FIL_TX	84	ı	Transmit channel filter analog ground					
AVSS_REF	87	ı	Reference analog ground					
CLKIN	42	ı	35.328 MHz VCXO clock input					
CLKOUT/INT	41	0	If CONFIG2 (pin 100) is low, this pin is 4.416 MHz clock output. If CONFIG2 is high, this pin functions as INT.					
COMPA_EC	63	0	EC channel cap input A. Add 500 pF X7R ceramic capacitor to AVDD1_EC.					
COMPB_EC	62	0	EC channel cap input B. Add 1 μF X7R ceramic capacitor to AVDD1_EC.					
COMPA_TX	68	0	TX channel decoupling cap input A. Add 500 pF ceramic capacitor to AVDD1_TX.					
COMPB_TX	69	0	TX channel decoupling cap input B. Add 1 μF ceramic capacitor to AVDD1_TX.					
CONFIG2	100	I	I/O configuration input pin. A high on this pin redefines the function of pins 37 and 41. The default state of this pin is low. Refer to Figure 3 for details.					
CS	51	ı	Parallel port chip select					
D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 D5 D4 D3 D2	34 (MSB) 33 32 31 30 29 28 25 24 23 22 21 20 19	1/0	Parallel port data bits D0=LSB					
D1 D0	18 17 (LSB)							



Terminal Functions(Continued)

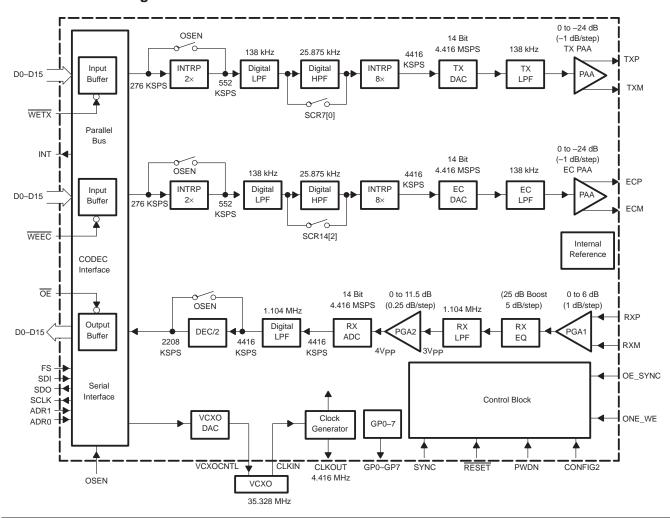
TERMINAL		1/0	DESCRIPTION				
NAME	NO.	"	DECOMM FION				
DVDD_BF	26		Digital I/O buffer supply				
DVDD_CLK	44	H	Digital clock supply				
DVDD_LG	47	H	Digital logic supply				
DVDD_RX	15	H	Receive channel digital power supply				
DVDD_DAC	57	l i	Digital power supply for DAC				
DVSS	9, 58	 	Digital ground				
DVSS_BF	27	H	Digital I/O buffer ground				
DVSS_CLK	43	H	Digital clock ground				
DVSS_LG	46	H	Digital logic ground				
DVSS_RX	16	H	Receive channel ground				
DVSS_DAC	56	H	DAC ground				
ECM	79	0	EC output minus				
ECP	78	0	EC output plus				
FS	38	Ī	Frame sync input				
GP7	8	 	Traine Syno input				
GP6	7						
GP5	6						
GP4 GP3	5 4	0	General-purpose output port				
GP2	3						
GP1	2						
GP0	1						
INT	40	0	Data rate clock (INT is 4.4 MHz when OSEN=1, 2.2 MHz when OSEN=0)				
NC	10, 14, 74, 75, 76, 77,		No connection. All the NC pins should be left open.				
	80, 85, 91,						
	97						
ŌĒ	50	I	Parallel port output enable from host processor				
OE_SYNC	99	ı	OE synchronized input. A high input will optimize the read operation from keep-out zone. The default state of this pin is low. See Figure 5 for details.				
ONE_WE	98	Т	TX and EC write combined input. A high on this pin allows pin 48, WETX, to be used to write to both the				
			EC and TX channels. In this case, after a hardware reset or write to SCR14[0], the first low-going pulse of				
			WETX will be a write to TX channel and the second one will be a write to EC channel. The default state of this pin is low.				
OSEN	39		Over-sampling enable input. OSEN=1 enables over-sampling mode (INT = 4.4 MHz).				
PWDN	53	H	Power-down input. When PWDN=0, device is in normal operating mode. When PWDN=1, device is in				
WEIT	00	'	power-down mode.				
REFM	89	0	Decoupling reference REF voltage minus. Add 10 μ F tantalum and 0.1 μ F ceramic capacitors to AVSS_REFP. The nominal dc voltage at this terminal is 0.5 V. See figure 9 for detail.				
REFP	88	0	Decoupling reference REF voltage plus. Add 10 μ F tantalum and 0.1 μ F ceramic capacitors to AVSS_REFM. The nominal dc voltage at this terminal is 2.5 V See figure 9 for detail.				
RESET	52	ı	H/W system reset. An low level will reset the device.				
RXM	96	ı	Receive RX input minus. RXM is self-biased to AVDD_FIL_RX/2.				
RXP	95	1	Receive RX input plus. RXP is self-biased to AVDD_FIL_RX/2.				
SCLK/READY	37	0	If CONFIG2 (pin 100) is low, this pin is serial clock output. If CONFIG2 is high, it indicates the period in which parallel data can be transferred.				
SDI	36	T	Serial data input				
	_						



Terminal Functions(Continued)

TERMIN	NAL	1/0	DESCRIPTION			
NAME	NO.	1/0	DESCRIPTION			
SDO	35	0	Serial data output			
SYNC	45	I	SYNC pulse for clock synchronization. A high pulse to the pin synchronizes the clock operation. The default state of the pin is low. Refer to Figure 4 for detail.			
TXM	82	0	Transmit output minus			
TXP	81	0	Transmit output plus			
VCXOCNTL	59	0	VCXO DAC output			
VMID_ADC	11	0	Decoupling 1.5 V for ADC. Add 10 μF tantalum and 0.1 μF ceramic capacitors to AVSS_ADC.			
VMID_REF	90	0	Decoupling 1.5 V reference voltage. Add 10 μF tantalum and 0.1 μF ceramic capacitors to AVSS_REF.			
Vss	92	-1	Substrate. VSS needs to connect to analog ground.			
WEEC/CS2	49	I	Write enable to EC channel from host processor, when ONE_WE (pin 98) is low. If ONE_WE is high, it functions as second chip select, CS2, and both CS and CS2 need to be low in order to have WETX access data on the parallel bus.			
WETX	48	I	Write enable for TX channel from host processor. If ONE_WE is high, it functions as write enable for both TX and EC after hardware reset or write to SCR14[0]. In this case, the first low-going pulse of WETX will be a write to TX channel, and the second one will be a write to EC channel			

functional block diagram



communication channels

transmitter channel/echo-cancellation channel

The transmitter channel is powered by a high performance DAC. This is a 4.416-MHz, 14-bit DAC that provides a 16X over-sampling to reduce DAC noise. The input buffer is sampled at either 276 KSPS (pin OSEN = low, default), or 552 KSPS (pin OSEN = high). A low-pass filter limits its output to 138 kHz. A programmable attenuator, with a range between 0 and -24 dB in -1-dB steps, drives the output into the external ADSL line driver.

A second transmitter is used to perform pre-echo cancellation. This analog echo cancellation helps reduce the dynamic range requirements of the RT receiver. It has the same function as the first transmitter channel. It drives a separate external line driver to perform the cancellation.

receiver channel

The receiver channel has two PGAs and an equalizer to match the loop loss and flatten the spectrum. This results in a reduction in dynamic range requirement for the high resolution ADC. The receiver channel also has a 1.104-MHz low-pass filter with a 4.416 MSPS and a 14-bit ADC to provide a 2X over-sampling. The output buffer is updated at either 2208 KSPS (pin OSEN = low, default), or 4416 KSPS (pin OSEN = high).

VCXO-control DAC

A 12-bit DAC is used to control the external 35.328-MHz VCXO (voltage control oscillator) that provides the system clock to the codec. In a typical application, the typical update rate of the DAC is about 4 kHz, depending on the ADSL frame rate. The host DSP initiates the update through the serial interface. The two 8-bit registers SCR4 and SCR5 (each 2s complement) are used to generate the 12-bit code for the DAC. This requires the use of 16 bits to obtain a 12-bit number. So the lower 4 bits of the MSB register (SCR5[3:0]) are added (2s complement) to the higher 4 bits of the LSB register (SCR4[7:4]). Refer to Figure 1 for code generation. The updated code is sent to the DAC two SCLKs after the SCR4 register is received. Notice that if SCR5 does not need to be updated, only one write cycle to SCR4 is needed to update the VCXO DAC. In this case, the lower 8 bits of the 12-bit word will be updated.

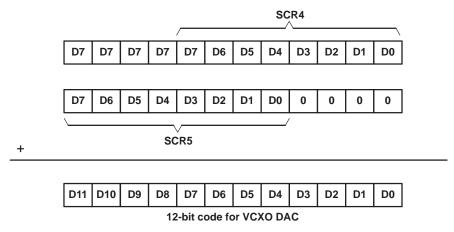


Figure 1. 12-Bit Code Generation for VCXO DAC



PRINCIPLES OF OPERATION

communication channels (continued)

clock generation

The clock generation block provides the necessary clock signals for the device, with minimum skew and jitter. This is closely dependent on the performance of the external VCXO. The external VCXO specifications are:

- 3.3 V supply
- 35.328 MHz ± 50 PPM
- Minimum duty cycle is 60/40 (50/50 is optimum)

The major clocks generated internally are shown in Table 1.

Table 1. Clock Description

CLOCK	FREQUENCY (MHz)				
	OSEN=0	OSEN=1			
INT	2.208	4.416			
CLKOUT	4.416	4.416			
SCLK	4.416	4.416			

INT

The interrupt (INT) to the host processor is 4.416 MHz when OSEN = 1 and 2.208 MHz when OSEN = 0.

SCLK

The serial clock used in the serial codec interface has a fixed frequency of 4.416 MHz and is synchronous with the master clock (35.328 MHz).

CLKOUT

CLKOUT is a 4.416-MHz clock output, and is synchronous with the master clock (35.328 MHz).

interface

parallel interface

The device has a 16-bit parallel interface for transmitter and receiver data. Strobes \overline{OE} , \overline{WETX} , and \overline{CS} from the host DSP are edge-triggered signals. An incoming signal is registered on the rising edge of $\overline{WETX}/\overline{WEEC}$. When ONE_WE is enabled, only \overline{WETX} is needed for both the transmit channel and the echo-cancellation channel write operation. After D0 of register SCR14 is programmed, the data from the first pulse of \overline{WETX} goes to the transmit channel, while the data from the second pulse of \overline{WETX} goes to the echo-cancellation channel. Output data from the codec is enabled after the falling edge of the \overline{OE} strobe, and disabled after the rising edge of the \overline{OE} strobe. The INT cycle time is hardware-configurable to 4.416 MHz (2X over-sampling mode, OSEN=1), or to 2.208 MHz (1X over-sampling mode, OSEN=0). SYNC is used to synchronize the operation between the codec and the host transceiver. SCLK/READY is used to indicate the parallel data transfer period in configuration mode 2. See Figure 3 for details.

OE SYNC is used to synchronize the codec timing to \overline{OE} . See Figure 5 for details.

For the 16-bit parallel data, D0 is the LSB and D15 is the MSB. The parallel TX and RX data contains 16 valid bits. All 16 bits are used in the digital filtering.



interface (continued)

keep-out zones

The last CLKIN cycle before a transition of CLKOUT is defined as a keep-out zone. These zones are reserved for the sampling of analog signals. All digital I/O (except for CLKIN) should be quiet during these keep-out zones.

over-sampling mode

The OSEN pin selects 2X over-sampling mode (INT running at 4.416 MHz), or 1X over-sampling mode (INT running at 2.208 MHz).

serial interface

The serial port is used for codec configuration and register reading. The word length is 16-bit. Two hardware configuration terminals, ADR[1:0], are used to configure the device ID. Up to four codecs can be identified for each common serial port. Refer to figure 6 for timing and format.

The master codec (ADR[1:0] = [0,0]) provides the SCLK to the host processor. The SCLK terminals on the other codecs are left unconnected. All the codecs in a multi-codec system should be synchronized so that their SCLK signals are in phase, even though the signals themselves are not being used. This ensures that, even though the individual SCLK signals of each codec are not being used, the data is being latched into the codec properly.

The SCLK is a continuously running 4.416-MHz fixed-frequency clock, synchronized to the codec internal events and CLKOUT (to the host) so that the keep-out zones may be monitored. A host DSP can drive the FS (synchronized to the CLKOUT from the codec) into the codec to initiate a 16-bit serial I/O frame.

If SCR5 needs to be updated, the host controller (DSP) must first write the SCR5 of the VCXO DAC data, and then the SCR4 of the VCXO DAC data. The VCXO DAC only gets updated after the SCR4 is written.

GP port

The general-purpose port provides eight outputs, each capable of delivering 0.5 mA, for control of external circuitry such as LEDs, gain control, and power down.

voltage reference

The built-in reference provides the required reference voltage and current to individual analog blocks. It is also brought out to external terminals for noise decoupling.



register programming (see Figure 6 for timing and format details)

Table 2. System Control Registers (SCR)

R	EGISTER		DEFAULT		
NAME	ADDRESS S3, S2, S1, S0	MODE	VALUE	FUNCTION	
SCR0	0000	R	00000000		
SCRU	0000	W		D0: S/W RESET (self clearing)	
SCR1	0001	R/W	00000000	D[4:0]=TX channel PAA gain select. D[4:0]=00000 for 0 dB D[4:0]=11000 for -24 dB	
SCR2	0010	R/W	00000000	D[5:0]=RX PGA2. D[5:0]=000000 for 0 dB. D[5:0]=101110 for 11.5 dB.	
SCR3	0011	R/W	00000000	D[2:0]= RX EQ slope select. D[2:0]=000 for 0dB/MHz, D[2:0]=001 for 5 dB/MHz, D[2:0]=101 for 25 dB/MHz	
SCR4	0100	R/W	00000000	D[7:0]=VCXODAC (low 8 bits of 12-bit DAC code)	
SCR5	0101	R/W	00000000	D[7:0]=VCXODAC (high 8 bits of 12-bit DAC code)	
SCR6	0110	R/W	00000000	D[7:0]=GP[7:0]	
SCR7	0111	R/W	00000000	MISC control (set to 1 to enable) D0: bypass TX DHPF (25.875 kHz) D1: S/W power-down RX channel D2: S/W power-down TX channel D3: analog loop-back (TX channel) D4: digital loop-back (TX and EC channel) D5: TX parallel interface (read-back) test mode enable D6: EC channel power down D7: EC analog loop-back	
SCR8	1000	R/W	00000000	D[4:0]=EC channel PAA gain select. D[4:0]=00000 for 0 dB. D[4:0]=11000 for -24 dB.	
SCR9	1001	R/W	00000000	D[7:0]=RX offset low	
SCR10	1010	R/W	00000000	D[7:0]=RX offset high	
SCR11	1011	R/W	00000000	D[4:0]=TX digital gain select. The gain range is -1dB to 1dB in 0.1 dB-steps. D[4:0]=00000 for 0 dB. D[4:0]=00001 for +0.1 dB. D[4:0]=01010 for +1 dB. D[4:0]=10000 for -1 dB. D[4:0]=11001 for -0.1 dB.	
SCR12	1100	R/W	00000000	D[2:0]=RX PGA1. D[2:0]=000 for 0 dB. D[2:0]=110 for 6 dB.	
SCR13	1101	R/W	00000000	D[4:0]=EC digital gain select. The gain range is -1dB to 1dB in 0.1-dB steps. D[4:0]=00000 for 0 dB. D[4:0]=00001 for +0.1 dB. D[4:0]=01010 for +1 dB. D[4:0]=10000 for -1 dB. D[4:0]=11001 for -0.1 dB.	
SCR14	1110	R/W	00000000	D0: Sync the write operation when ONE_WE is selected. After D0 is set to 1, the first pulse of WETX goes to TX channel, and the second pulse goes to EC channel. The bit will be self-cleared to 0. D1: enable FIFO (first-in, first-out). See Note 1. D2: Bypass EC DHPF (25.875 kHz) D3: ECNULL. When D3 is set to 1, ECP and ECM are connected to weakly driven mid supply. It can only be used during EC power-down mode.	

NOTE 1: It is a two-stage FIFO buffer, and can store up to two write-samples if asynchronous write operation is required.

SCR0 - system control register

SCR	0 - s	yster	n cor	ntrol	regis	ter		Addre	ss:0000b Contents at reset: 00000000b
D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION
0	0	0	0	0	0	0	1	01	S/W reset (self clearing). All control registers are set to reset content.



register programming (continued)

SCR1 – TX PAA control register Address:0001b Contents at reset: 00000000b

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION
0	0	0	0	0	0	0	0	00	TX PAA gain = 0 dB
0	0	0	0	0	0	0	1	01	TX PAA gain = -1 dB
0	0	0	0	0	0	1	0	02	TX PAA gain = -2 dB
0	0	0	0	0	0	1	1	03	TX PAA gain = -3 dB
0	0	0	0	0	1	0	0	04	TX PAA gain = -4 dB
0	0	0	0	0	1	0	1	05	TX PAA gain = -5 dB
0	0	0	0	0	1	1	0	06	TX PAA gain = -6 dB
0	0	0	0	0	1	1	1	07	TX PAA gain = -7 dB
0	0	0	0	1	0	0	0	08	TX PAA gain = -8 dB
0	0	0	0	1	0	0	1	09	TX PAA gain = -9 dB
0	0	0	0	1	0	1	0	0A	TX PAA gain = -10 dB
0	0	0	0	1	0	1	1	0B	TX PAA gain = -11 dB
0	0	0	0	1	1	0	0	0C	TX PAA gain = -12 dB
0	0	0	0	1	1	0	1	0D	TX PAA gain = -13 dB
0	0	0	0	1	1	1	0	0E	TX PAA gain = -14 dB
0	0	0	0	1	1	1	1	0F	TX PAA gain = -15 dB
0	0	0	1	0	0	0	0	10	TX PAA gain = -16 dB
0	0	0	1	0	0	0	1	11	TX PAA gain = -17 dB
0	0	0	1	0	0	1	0	12	TX PAA gain = -18 dB
0	0	0	1	0	0	1	1	13	TX PAA gain = -19 dB
0	0	0	1	0	1	0	0	14	TX PAA gain = -20 dB
0	0	0	1	0	1	0	1	15	TX PAA gain = -21 dB
0	0	0	1	0	1	1	0	16	TX PAA gain = -22 dB
0	0	0	1	0	1	1	1	17	TX PAA gain = -23 dB
0	0	0	1	1	0	0	0	18	TX PAA gain = -24 dB
_	_	_	_	_	_	_	_	19–FF	TX PAA gain = −24 dB



register programming (continued)

SCR2 – RX PGA2 control register Address:0010b Contents at reset: 00000000b

					_	,			
D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION
0	0	0	0	0	0	0	0	00	RX PGA2 = 0 dB
0	0	0	0	0	0	0	1	01	RX PGA2 = 0.25 dB
0	0	0	0	0	0	1	0	02	RX PGA2 = 0.5 dB
0	0	0	0	0	0	1	1	03	RX PGA2 = 0.75 dB
0	0	0	0	0	1	0	1	05	RX PGA2 = 1 dB
0	0	0	0	0	1	1	0	06	RX PGA2 = 1.25 dB
0	0	0	0	0	1	1	1	07	RX PGA2 = 1.5 dB
0	0	0	0	1	0	0	0	08	RX PGA2 = 1.75 dB
0	0	0	0	1	0	0	1	09	RX PGA2 = 2 dB
0	0	0	0	1	0	1	0	0A	RX PGA2 = 2.25 dB
0	0	0	0	1	0	1	1	0B	RX PGA2 = 2.5 dB
0	0	0	0	1	1	0	0	0C	RX PGA2 = 2.75 dB
0	0	0	0	1	1	0	1	0D	RX PGA2 = 3 dB
0	0	0	0	1	1	1	0	0E	RX PGA2 = 3.25 dB
0	0	0	0	1	1	1	1	0F	RX PGA2 = 3.5 dB
0	0	0	1	0	0	0	0	10	RX PGA2 = 3.75 dB
0	0	0	1	0	0	0	1	11	RX PGA2 = 4 dB
0	0	0	1	0	0	1	0	12	RX PGA2 = 4.25 dB
0	0	0	1	0	0	1	1	13	RX PGA2 = 4.5 dB
0	0	0	1	0	1	0	0	14	RX PGA2 = 4.75 dB
0	0	0	1	0	1	0	1	15	RX PGA2 = 5 dB
0	0	0	1	0	1	1	0	16	RX PGA2 = 5.25 dB
0	0	0	1	0	1	1	1	17	RX PGA2 = 5.5 dB
0	0	0	1	1	0	0	0	18	RX PGA2 = 5.75 dB
0	0	0	1	1	0	0	1	19	RX PGA2 = 6 dB
0	0	0	1	1	0	1	0	1A	RX PGA2 = 6.25 dB
0	0	0	1	1	0	1	1	1B	RX PGA2 = 6.5 dB
0	0	0	1	1	1	0	0	1C	RX PGA2 = 6.75 dB
0	0	0	1	1	1	0	1	1D	RX PGA2 = 7 dB
0	0	0	1	1	1	1	0	1E	RX PGA2 = 7.25 dB
0	0	0	1	1	1	1	1	1F	RX PGA2 = 7.5 dB
0	0	1	0	0	0	0	0	20	RX PGA2 = 7.75 dB
0	0	1	0	0	0	0	1	21	RX PGA2 = 8 dB
0	0	1	0	0	0	1	0	22	RX PGA2 = 8 25dB
0	0	1	0	0	0	1	1	23	RX PGA2 = 8.5 dB
0	0	1	0	0	1	0	0	24	RX PGA2 = 8.75 dB
0	0	1	0	0	1	0	1	25	RX PGA2 = 9 dB
0	0	0	0	0	1	0	0	04	RX PGA2 = 9.25 dB
0	0	1	0	0	1	1	0	26	RX PGA2 = 9.5 dB
0	0	1	0	0	1	1	1	27	RX PGA2 = 9.75 dB
0	0	1	0	1	0	0	0	28	RX PGA2 = 10 dB
0	0	1	0	1	0	0	1	29	RX PGA2 = 10.25 dB
	-								



register programming (continued)

SCR2 – RX PGA2 control register (continued) Address:0010b Contents at reset: 00000000b

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION
0	0	1	0	1	0	1	0	2A	RX PGA2 = 10.5 dB
0	0	1	0	1	0	1	1	2B	RX PGA2 = 10.75 dB
0	0	1	0	1	1	0	0	2C	RX PGA2 = 11 dB
0	0	1	0	1	1	0	1	2D	RX PGA2 = 11.25 dB
0	0	1	0	1	1	1	0	2E	RX PGA2 = 11.5 dB
_	_	_	_	_	_	_	_	2F–FF	RX PGA2 = 11.5 dB

SCR3 – RX EQ control register Address:0011b Contents at reset: 00000000b

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION
0	0	0	0	0	0	0	0	00	RX EQ = 0 dB/MHz
0	0	0	0	0	0	0	1	01	RX EQ = 5 dB/MHz
0	0	0	0	0	0	1	0	02	RX EQ = 10 dB/MHz
0	0	0	0	0	0	1	1	03	RX EQ = 15 dB/MHz
0	0	0	0	0	1	0	0	04	RX EQ = 20 dB/MHz
0	0	0	0	0	1	0	1	05	RX EQ = 25 dB/MHz
_	_	_	_	_	_	_	_	06-FF	RX EQ = 25 dB/MHz

SCR4 – VCXO data register Address:0100b Contents at reset: 00000000b SCR5 – VCXO data register Address:0101b Contents at reset: 00000000b

The following table shows some representative analog outputs. Notice that the read-back values of SCR4 and SCR5 are different from the values written in.

Table 3. VCXODAC Digital-Analog Mapping

OPERATION	HEX RESULT	ANALOG OUTPUT (see Note 2 and 3)	COMMENTS
	0x800	0 V	Min scale
	0x801	ΔV	Just above min
	0xFFF	2047 ΔV	Just below mid
SRC5[7:0] × 2 ⁴ + SCR4[7:0]	0x000	2048 ΔV	Mid scale
	0x001	2049 ΔV	Just above mid
	0x7FE	4094 ΔV	Just below max
	0x7FF	4095 ∆V	Max scale

NOTES: 2. $\Delta = (3/4095) \text{ V}$

3. The analog output is computed as follows: $((SCR\%[7:0] \times 2^4 + SCR4[7:0])) + 2048(decimal) \times \Delta$



PRINCIPLES OF OPERATION

register programming (continued)

examples:

- Positive SCR5 + positive SCR4
 (0x24 × 2⁴ + 0x42) = 0×240 + 0×42 = 0×282 = 642 decimal
 Analog output = (642 + 2048) ΔV = 2690 ΔV = 1.971 V

 The read back values of SCR5 and SCR4 are 0×02 and 0×82
- Positive SCR5 + negative SCR4
 (0x24 × 2⁴ + 0×C2) = 0×240 + 0×FC2 = 0×202 = 514 decimal
 Analog output = (514 + 2048) ΔV = 2562 ΔV = 1.877 V
 The read back values of SCR5 and SCR4 are 0×02 and 0×02
- Negative SCR5 + positive SCR4 $(0xA2 \times 2^4 + 0\times42) = 0\times A20 + 0\times42 = 0\times A62 = -1438$ decimal Analog output = (-1438 + 2048) $\Delta V = 610$ $\Delta V = 0.447$ V The read back values of SCR5 and SCR4 are $0\times0A$ and 0×62
- Negative SCR5 + negative SCR4
 (0xA2 × 2⁴ + 0×C2) = 0×A20 + 0×FC2 = 0×9E2 = -1566 decimal
 Analog output = (-1566 + 2048) ΔV = 482 ΔV = 0.353 V

 The read back values of SCR5 and SCR4 are 0×09 and 0×E2

SCR6 – general-purpose output data register Address:0110b Contents at reset: 00000000b

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION
0/1	-	-	-	-	-	-	-		GP7 = low(0)/high(1)
_	0/1	-	_	-	_	-	1		GP6 = low(0)/high(1)
_	-	0/1	-	-	_	ı	ı		GP5 = low(0)/high(1)
_	-	-	0/1	-	-	ı	ı		GP4 = low(0)/high(1)
_	-	-	-	0/1	-	ı	ı		GP3 = low(0)/high(1)
_	-	-	-	-	0/1	-	-		GP2 = low(0)/high(1)
_	_	_	-	_	-	0/1	-		GP1 = low(0)/high(1)
_	_	_	_	_	_	-	0/1		GP0 = low(0)/high(1)

register programming (continued)

SCR7 – miscellaneous control register 1 Address:0111b Contents at reset: 00000000b

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION		
-	-	-	_	_	-	-	1		Bypass TX DHPF (25.875 kHz)		
_	_	_	_	_	_	1	_		S/W power-down RX channel		
_	_	_	_	_	1	_	_		S/W power-down TX channel		
_	_	_	_	1	_	_	_		Analog loop-back (TX channel) (see Note 4)		
_	_	_	1	_	_	_	_		Digital loop-back (TX and EC channel) (see Note 5)		
_	_	1	_	_	_	_	_		TX parallel interface (read back) test mode enable (see Note 6)		
_	1	_	_	_	_	_	_		EC channel power down		
1	_	_	_	_	_	_	_		EC analog loop-back		

NOTES: 4. Analog loop-back: Analog output pins (TXP/TXM or ECP/ECM) are internally connected to RXP/RXM.

- 5. Digital loop-back: RX digital output buffer (16-bit word) is internally connected to the TX/EC digital input buffer.
- 6. The input digital data is read back from RX output buffer without going through DAC converter.

SCR8 – EC PAA control register Address: 1000b Contents at reset: 00000000b

SCR8 shares the same format with SCR1. Check with SCR1 for detail

SCR9 – RX offset control register[7:0] Address:1001b Contents at reset: 00000000b SCR10 – RX offset control register [15:8] Address:1010b Contents at reset: 00000000b

These two registers are concatenated to form a 16-bit word in 2s complement data format. The 16-bit word is used to adjust RX channel dc offset error. It adds to the 16-bit data from the RX digital filter before the data goes to the RX output buffer.



register programming (continued)

SCR11 – TX channel digital gain control register Address: 1011b Contents at reset: 00000000b (see Note 7)

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION	
0	0	0	1	1	0	0	1	19	TX digital gain = -0.1 dB	
0	0	0	1	1	0	0	0	18	TX digital gain = -0.2 dB	
0	0	0	1	0	1	1	1	17	TX digital gain = -0.3 dB	
0	0	0	1	0	1	1	0	16	TX digital gain = -0.4 dB	
0	0	0	1	0	1	0	1	15	TX digital gain = -0.5 dB	
0	0	0	1	0	1	0	0	14	TX digital gain = -0.6 dB	
0	0	0	1	0	0	1	1	13	TX digital gain = -0.7 dB	
0	0	0	1	0	0	1	0	12	TX digital gain = -0.8 dB	
0	0	0	1	0	0	0	1	11	TX digital gain = -0.9 dB	
0	0	0	1	0	0	0	0	10	TX digital gain = −1 dB	
0	0	0	0	0	0	0	0	00	TX digital gain = 0 dB	
0	0	0	0	0	0	0	1	01	TX digital gain = 0.1 dB	
0	0	0	0	0	0	1	0	02	TX digital gain = 0.2 dB	
0	0	0	0	0	0	1	1	03	TX digital gain = 0.3 dB	
0	0	0	0	0	1	0	0	04	TX digital gain = 0.4 dB	
0	0	0	0	0	1	0	1	05	TX digital gain = 0.5 dB	
0	0	0	0	0	1	1	0	06	TX digital gain = 0.6 dB	
0	0	0	0	0	1	1	1	07	TX digital gain = 0.7 dB	
0	0	0	0	1	0	0	0	08	TX digital gain = 0.8 dB	
0	0	0	0	1	0	0	1	09	TX digital gain = 0.9 dB	
0	0	0	0	1	0	1	0	0A	TX digital gain = 1 dB	
_	_	_	_	_	_	_	_	All others	Reserved (see Note 8)	

NOTES: 7. Digital gain is used to compensate the TX channel gain error.

SCR12 – RX PGA1 control register Address:1100b Contents at reset: 00000000b

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION
0	0	0	0	0	0	0	0	00	RX PGA1 = 0 dB
0	0	0	0	0	0	0	1	01	RX PGA1 = 1 dB
0	0	0	0	0	0	1	0	02	RX PGA1 = 2 dB
0	0	0	0	0	0	1	1	03	RX PGA1 = 3 dB
0	0	0	0	0	1	0	0	04	RX PGA1 = 4 dB
0	0	0	0	0	1	0	1	05	RX PGA1 = 5 dB
0	0	0	0	0	1	1	0	06	RX PGA1 = 6 dB
_	_	_	_	_	_	_	_	07-FF	RX PGA1 = 6 dB



^{8.} Performance of the codec for invalid combination of bits should not be used. The user should make no assumption that the code bits will saturate to a maximum or minimum value or wrap around to a valid combination.

register programming (continued)

SCR13 – EC channel digital gain control register Address:1101b Contents at reset: 00000000b

SCR13 has the same format as SCR11. Check with SCR11 for details.

SCR14 – Miscellaneous control register 2 Address:1110b Contents at reset: 00000000b

D7	D6	D5	D4	D3	D2	D1	D0	REGISTER VALUE (HEX)	DESCRIPTION	
0	0	0	0	-	_	_	1		One write operation reset. (see Note 9)	
0	0	0	0	-	_	1	_		Enable FIFO	
0	0	0	0	_	1	_	_		Bypass EC DHPF (25.875 kHz)	
0	0	0	0	1	-	-	-		ECP and ECM are connected to weakly driven mid-supply. It can only be used during EC power-down mode.	

NOTE 9: Write-synchronized operation: A 1 is written to bit D0 of SCR14 register after pin ONE_WE is set to high. This sets the start point for the TX/EC operation. During the first WETX pulse, data is written to the TX channel. During the second WETX pulse, data is written to the EC channel. D0 of SCR14 is always self-cleared; therefore, the read-back value of bit D0 of SCR14 is always zero.

device initialization time

The TLV320AD11A completes all calibration and initialization in less than 1 second. This includes reference settling time (≈950 μs), one rest after power up (1 serial frame), VCXODAC configuration (2 serial frames), TX/RX gain select (4 serial frames), and self-calibration of the DAC (256X113 ns). Each 16-bit frame requires up to 5 μs. The host processor needs to initiate this process upon a successful power up.

power-down

Both hardware and software power-down modes are provided. The serial interface is operative when the codec is in power-down mode. By sending commands through serial interface, either the codec or part of the codec. can be software powered down. All the references are kept on in the software power-down mode. The codec can also be hardware powered down by setting PWDN pin to high. All the references are shut off in the hardware power-down mode. The contents of the registers will not change in either power-down modes.

power supply grouping recommendation

The following power supply grouping is recommended for best performance of this device. Ferrite beads are used to separate group 1, group 2, and group 3 if the same 3.3-V analog power source is shared

- Group 1: AVDD_FIL_TX, AVDD_FIL_EC, AVDD1_TX, AVDD2_TX, AVDD1_EC, AVDD2_EC
- Group 2: AVDD FIL RX, AVDD ADC
- Group 3: AVDD REF
- Group 4: DVDD BF, DVDD CLK, DVDD LG, DVDD RX, DVDD DAC



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, AVDD to AGND, DVDD to DGND	
Analog input voltage range to AGND	0.3 V to AVDD+0.3 V
Digital input voltage range to DGND	0.3 V to DVDD+0.3 V
Operating virtual junction temperature range, T _J	–40°C to 150°C
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{str}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

power supply

		MIN	NOM	MAX	UNIT
Supply voltage	AVDD_FIL_TX, AVDD_FIL_EC, AVDD1_TX, AVDD2_TX, AVDD1_EC, AVDD2_EC; AVDD_FIL_RX, AVDD_ADC; AVDD_REF	3	3.3	3.6	V
	DVDD_BF, DVDD_CLK, DVDD_LG, DVDD_RX, DVDD_DAC	3	3.3	3.6	

digital inputs

		MIN	NOM	MAX	UNIT
High-level input voltage, VIH	I _I = 0.75 mA	2			\/
Low-level input voltage, V _{IL}	$I_{I} = -0.75 \text{ mA}$			0.8	V

analog input

		MIN	NOM	MAX	UNIT
Analog input signal range	AVDD_FIL_RX = 3.3 V. The input signal is measured single-ended.	AVDD.	_FIL_RX/2	±0.75	V
	AVDD_FIL_RX = 3.3 V. The input signal is measured differentially.		3		Vp–р

clock inputs

		MIN	NOM	MAX	UNIT
Input clock frequency	DVDD CLK=3.3 V		35.328		MHz
Input clock duty cycle	DVDD_CLN=3.3 V		50%		



electrical characteristics over recommended operating free-air temperature range, typical at T_A = 25°C, f_{CLKIN} = 35.328 MHz, analog power supply = 3.3 V, digital power supply = 3.3 V (unless otherwise noted)

TX and EC channel (measured differentially unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Signal bandwidth		T	138		kHz
	Conversion rate	OSEN pin high	T	4.416		MHz
	Conversion rate	OSEN pin low	2.208			IVIIIZ
	Channel gain error	PAA = 0 dB, Input = 99.1875 kHz at 06 dB	-0.1		0.1	dB
	PAA step gain error		-0.2		0.2	dB
	DC offset		-70		70	mV
	Cross-talk	RX to TX channel (43.125 kHz at -1 dB)		-65		dB
	Group delay			6		μs
	Power supply reject ratio (PSRR)	200 mVpp at 99.1875 kHz		50		dB
	Full cools output valtors	Load = 2000 Ω , single-ended measured	AVI	DD_TX/2	2±0.75	V
	Full scale output voltage	Load = 4000 Ω , differentially measured		3		Vp-p
AC Pe	rformance					
SNR	Signal-to-noise ratio			81		dB
THD	Total harmonic distortion ratio	43.125 kHz at -1 dB (see Note 10)		86		dB
TSNR	Signal-to-noise + harmonic distortion ratio			80		dB
MT	Missing-tone test (see Note 11)	120.750 kHz (missing-tone)		76		dB
Chann	el Frequency Response (refer to Figure 7)	-				
		30 kHz	-0.25		0.25	
	Gain relative to gain at 99.1875	60 kHz	-0.25		0.25	dB
	(25.875 kHz DHPF is bypassed)	138 kHz		gB		
		276 kHz		-55		

NOTES: 10. The input signal is the digital equivalent of a sine wave (digital full scale = 0 dB). The nominal differential output with this input condition is 3 Vpp.

reference outputs (see Note 12)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
REFP	REF plus input voltage			2.5		
REFM	REF minus input voltage	AVDD REF = 3.3 V		0.5		\ \
VMID_REF	REF mid input voltage	AVDD_REF = 3.3 V		1.5		V
VMID_ADC	Receive channel mid-input voltage			1.5		

NOTE 12: All the reference outputs should not be used as voltage source.

digital outputs

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VOH	High-level output voltage	I _{OH} = 0.5 mA	2.4			V
VOL	Low-level output voltage	$I_{OL} = -0.5 \text{ mA}$			0.6	V



^{11. 27} tones, 25.875 to 138 kHz, 4.3125 kHz/step, $-1\ dB$

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted), typical at $T_A = 25^{\circ}C$, $f_{CLKIN} = 35.328$ MHz, analog power supply = 3.3 V, digital power supply = 3.3 V (unless otherwise noted) (continued)

RX channel (measured differentially unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT			
	Signal bandwidth			1104		kHz			
	Conversion rate			4.416		MHz			
	Channel gain error	PGA1 = 0 dB, PGA2 = 2.5 dB, Input = 99.1875 kHz at -1 dB	-1.5		1.5	dB			
	PGA gain error	PGA1 (0 to 6 dB at 1 dB/step)	-0.2	0.2		dB			
	FGA gain enoi	PGA2 (2.5 to 14 dB at 0.25 dB/step)	-0.03		0.03	uБ			
	DC offset	PGA1 = 0 dB, PGA2 = 2.5 dB		3		mV			
	Crosstalk	TX to RX channel (99.1875 kHz at –1 dB see Note 13)		63		dB			
	Group delay			8		μs			
	Common mode reject ratio (CMRR)	99.1875 kHz at -1 dB		70		dB			
	Power supply reject ratio (PSRR)	200 mVpp at 99.1875 kHz		50					
	Analog input self-bias dc voltage		AVDD_FIL_RX/2±0.75			V			
	Input impedance			10		kΩ			
AC Performance									
SNR	Signal-to-noise ratio		68						
THD	Total harmonic distortion ratio	99.1875 kHz at 0 dB		77		dB			
TSNR	Signal-to-noise + harmonic distortion ratio	7		68					
МТ	Minimum (no. 1001 (no. No. 44)	120.750 kHz (missing-tone)	T	66		dB			
IVII	Missing-tone test (see Note 14)	750.375 kHz (missing-tone)		66		uБ			
Chann	el Frequency Response (EQ[2:0] = 0 dB/MHz)	(refer to Figure 8)							
		60 kHz	-0.25		0.25				
	Gain relative to gain at 99.1875 kHz	300 kHz	-0.25		0.25	dB			
	-	800 kHz		1		ub			
		1000 kHz		0.7					

NOTES: 13. The analog input test signal is a sine wave with 0 dB = 3 Vpp as the reference level.

VCXO DAC

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Resolution			12		Bits
DNL	Differential nonlinearity			±1		LSB
INL	Integral nonlinearity			±4		LSB
	Offset error			30		mV
Analog output	Full scale output voltage	Load = $50 \text{ k}\Omega$ and V_{DD} = 3.3 V		3		V

power dissipation

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Active mode			800	850	
Power dissipation	Power-down mode	Hardware power down		65		mW
	Fower-down mode	Software power down		70	·	



^{14. 250} tones, 25.875 to 1104 kHz, 4.3125 kHz/step, 0 dB.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

parallel port (see Figures 2, 3, and 4)

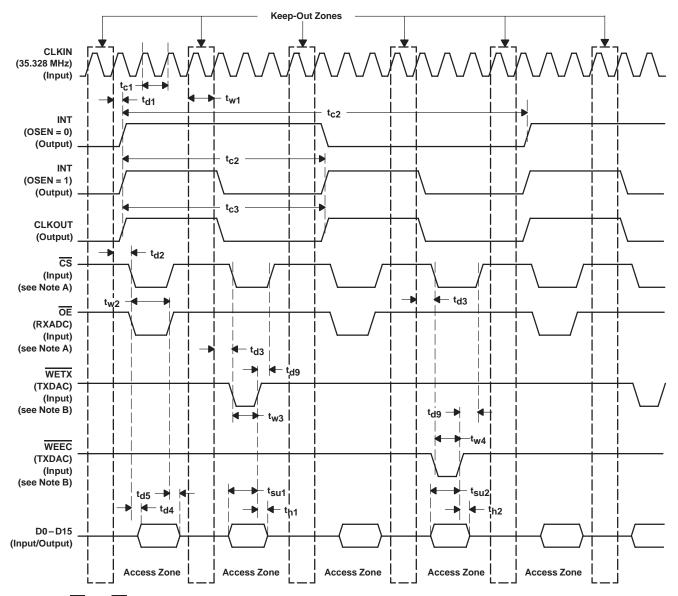
		PARAMETER	MIN	TYP	MAX	UNIT
t _{c1}	Period, CLKIN			28.3		ns
	Cycle time, INT	OSEN=0		16		
t _{c2}		OSEN=1		8		CLKIN
t _{c3}	Period, CLKOUT			8		
t _{d1}	Delay time, keep-out a	zone end to INT↑			5	ns
t _{d2}	Delay time, keep-out a	zone end (CLKIN↑) to OE↓/CS↓	0			ns
t _{d3}	Delay time, keep-out a	zone end to WETX↓/CS↓ or WEEC↓/CS↓	0			ns
t _{d4}	Delay time, data valid	after OE ↓ /CS ↓			15	ns
t _{d5}	Delay time, data beco	mes Hi-Z after OE↑/CS↑			5	ns
t _{d6}	Delay time, keep-out a	zone end to SCLK/READY↑		14.2		ns
t _{d7}	Delay time, SCLK/RE	ADY↓ to keep-out zone		14.2		ns
t _{d9}	Delay time, time between	een the rising edge of WETX/WEEC to the rising edge of CS	5			ns
t _{h1}	Hold time, data valid a	ıfter WETX↑	5			ns
t _{h2}	Hold time, data valid a	ifter WEEC↑	5			ns
t _{h3}	Hold time, SYNC keep	high after CLKIN↑	5			ns
t _{su1}	Setup time, data valid	before WETX↑	15			ns
t _{su2}	Setup time, data valid	before WEEC↑ or second WETX↑	15			ns
t _{su3}	Setup time, SYNC is h	nigh before CLKIN↑	10			ns
t _{w1}	Pulse width, keep-out	zone time		1		CLKIN
t _{w2}	Pulse width, OE		20			ns
t _{w3}	Pulse width, WETX or	WETX first pulse	28			ns
t _{w4}	Pulse width, WEEC or	WETX second pulse	28			ns
t _{w5}	Pulse width, SYNC			28		ns

serial port (see Figure 6)

	PARAMETER	MIN	TYP	MAX	UNIT
t _{c4}	Cycle time, SCLK		8		CLKIN
t _{d8}	Delay time, SCLK rising edge to SDO valid			15	ns
t _{h4}	Hold time, FS keep high after SCLK↓	5			ns
t _{h5}	SDI valid after SCLK↓	5			ns
t _{su4}	Setup time, FS valid before SCLK↓	20			ns
t _{su5}	SDI valid before SCLK↓	20			ns
t _{w6}	FS pulse width		28	·	ns



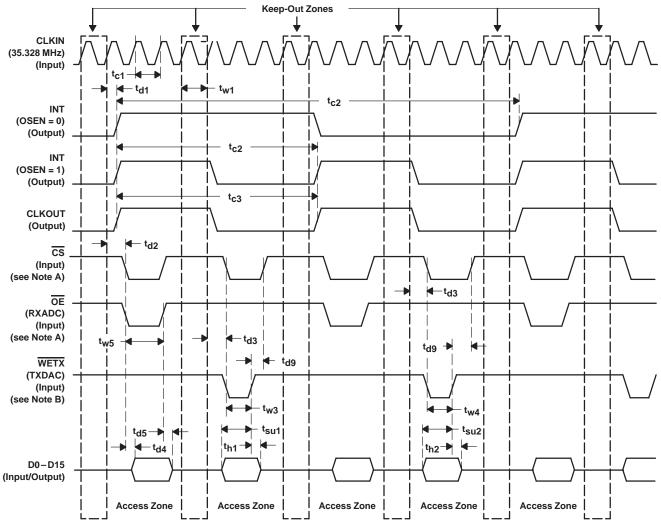
CONFIG2=0 or floating



- NOTES: A. $\overline{\text{CS}}$ AND $\overline{\text{OE}}$ may fall/rise together or be skewed from each other. It does <u>not</u> matter which falls/rises first. However, t_{d4} is referenced from whichever falls last, and t_{d5} is referenced from whichever rises first. $\overline{\text{CS}}$ can be connected to low if the parallel bus is not shared.
 - B. CS and WETX/WEEC may fall together or be skewed from each other. But the rising edge of WETX and WEEC should occur prior to the rising edge of CS.
 - C. The minimum update rate for TX and EC channel is 276 kHz in normal mode, and 552 kHz in over-sampling mode. The write operation for Tx and EC can occur at any time, if they do not conflict with each other or the Rx read cycle.

Figure 2. Parallel Timing Diagram

CONFIG2=1 and ONE_WE selected



- NOTES: A. $\overline{\text{CS}}$ AND $\overline{\text{OE}}$ may fall/rise together or be skewed from each other. It does <u>not</u> matter which falls/rises first. However, t_{d4} is referenced from whichever falls last, and t_{d5} is referenced from whichever rises first. $\overline{\text{CS}}$ can be connected to low if the parallel bus is not shared.
 - B. \overline{CS} and \overline{WETX} may fall together or be skewed from each other. But the rising edge of \overline{WETX} and \overline{WEEC} should occur prior to the rising edge of \overline{CS} .
 - C. The minimum update rate for TX and EC channel is 276 kHz in normal mode, and 552 kHz in over-sampling mode. The write operation for Tx and EC can occur at any time, if they do not conflict with each other or the Rx read cycle.

Figure 3. Parallel Timing Diagram



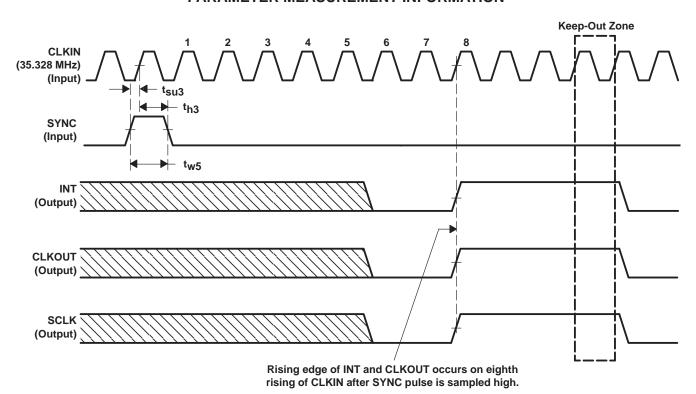
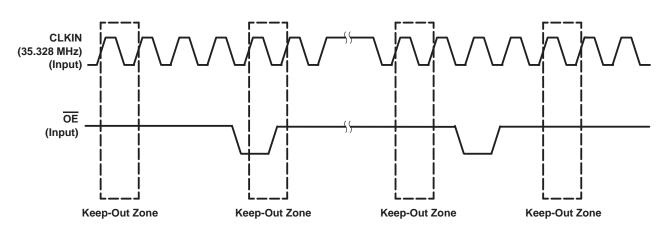


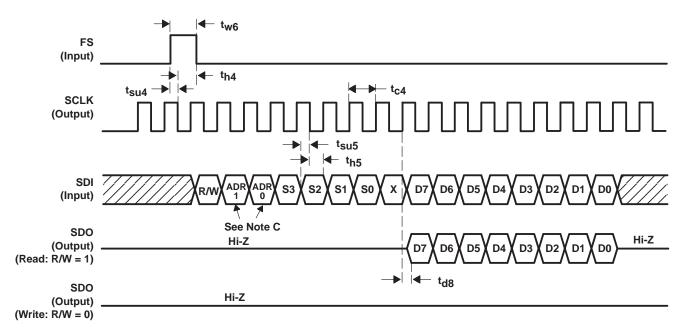
Figure 4. SYNC Pulse Timing



NOTES: A. It takes about 16 CLKINs to shift the keep-out-zone out of the $\overline{\text{OE}}$ pulse.

B. $\overline{\text{OE}}$ need to be periodic signal.

Figure 5. OE_SYNC Pulse Timing (OE_SYNC is set to high)



NOTES: A. Data on SDI is latched at the falling edge of SCLK.

B. Data is sent to SDO at the rising edge of SCLK.

C. ADR0 and ADR1 are the hardware configurable of ADR0 and ADR1 input pins.

Figure 6. Serial Port Timing

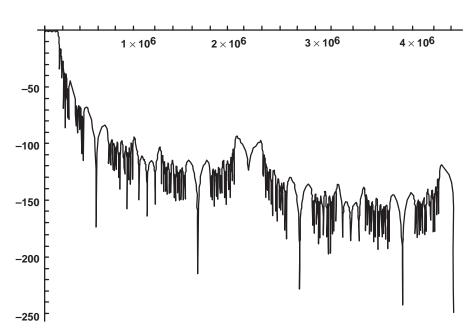


Figure 7. TX/EC Channel Filter Response (25.875 kHz DHPF is bypassed)



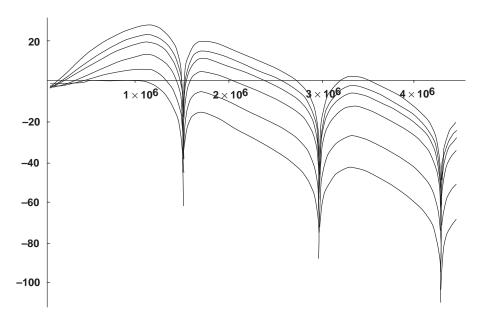


Figure 8. RX Channel Filter Response With Different Equalizer Setting

APPLICATION INFORMATION

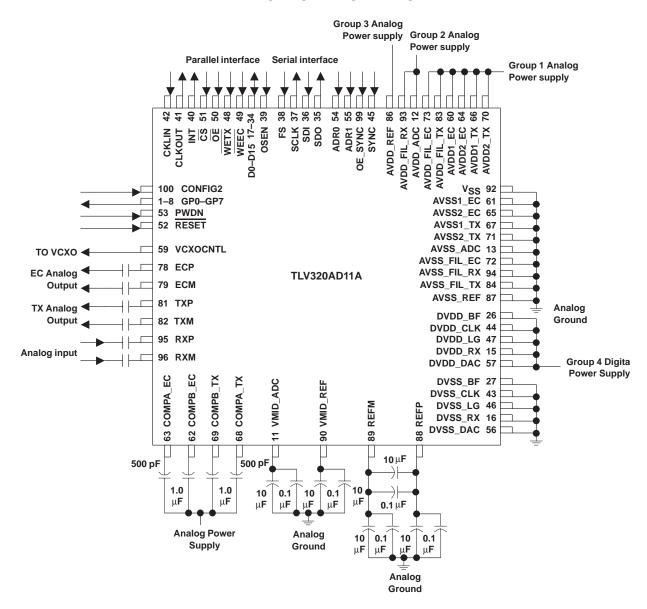
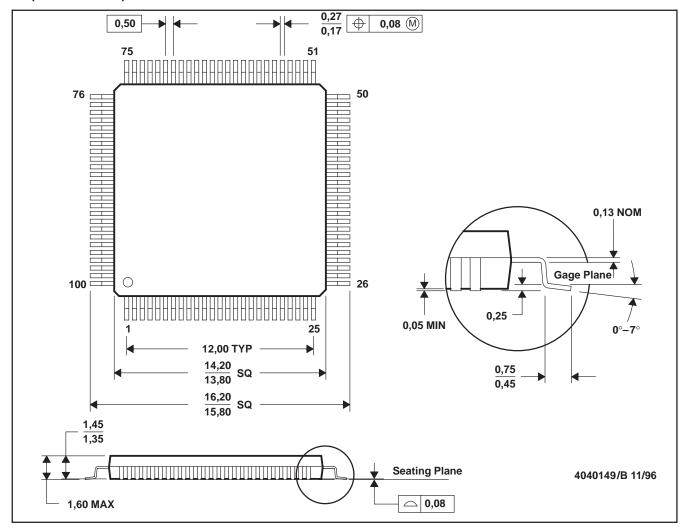


Figure 9. Typical Chip Configuration

MECHANICAL DATA

PZ (S-PQFP-G100)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-026

thermal resistance characteristics (S-PQFP package)

NO		°C/W	AIR FLOW LFPM
1	R1 _{JC} Junction-to-case	5.40	N/A
2	R1 _{JC} Junction-to-free air	30.4	0
3	R1 _{JC} Junction-to-free air	24.2	100
4	R1 _{JC} Junction-to-free air	22.3	250
5	R1 _{JC} Junction-to-free air	20	500

TLFPM - Linear feet per minute

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